RER1805 for PCN10630
ST SG9 (Singapore) additional source for STM8S001x, STM8S103x and STM8S903x

**Reliability Evaluation Plan** 

May 17<sup>th</sup>, 2018

products

MDG Quality & Reliability Department



## RERMCD1805 – F9GO1 Technology -Transfer to ST SG9 (Singapore) STM8S Die Test Vehicles

Die Vehicle	Process Perimeter	Assembly Line	Package	Number of Reliability Lots	
767		MUAR	LQFP7*7 32L	3 lots to qualify Process Perimeter	
765	F9G01	MUAR	LQFP14*14 80L		
766		JSCC	LQFP7*7 48L	Then 1 lot by Die	



## RERMCD1805 – F9GO1 Technology Transfer to ST SG9 (Singapore) STM8S Die Reliability Trials

Reliability Trial & Standard		Test Conditions	Pass Criteria	Lot Strategy	Units per Lot
ESD HBM	0060102 JESD22-A114ANSI/ESDA JEDEC JS-001	25°C	2kV (class 2)	1 to 3 lots	3
ESD CDM	ESD Charged Device Model ANSI/ESD STM5.3.1	Aligned with device datasheet	250V to 500V	1 lot	3
LU	0018695 JESD78	125°C REG-ON Configuration 125°C REG-OFF Configuration	No concern	1 to 3 lots	3 3
EDR + Bake	JESD22-A117 JESD22-A103	125°C & 3.6V Cycling 150°C Bake	10k cycles 1500h 1000h	1 to 3 lots 1 <sup>st</sup> lot 2 <sup>nd</sup> & 3 <sup>rd</sup> if any	77
EDR + Bake	JESD22-A117 JESD22-A103	25°C & 3.6V Cycling 150°C Bake	10k cycles 168h	1 to 3 lots	77
EDR + Bake	JESD22-A117 JESD22-A103	-40°C & 3.6V Cycling 150°C Bake	10k cycles 168h	1 to 3 lots	77
ELFR	MIL-STD-883 Method 1005 JESD22-A108 JESD74	125°C & 3.6V	48h	1 to 3 lots	500 units min per lot Total of 2000 units
HTOL	MIL-STD-883 Method 1005 JESD22-A108	125°C & 3.6V 100MHz	1200h 600h	1 <sup>st</sup> lot 2 <sup>nd</sup> & 3 <sup>rd</sup> if any	77



# RERMCD1805 – F9GO1 Technology Transfer to ST SG9 (Singapore) STM8S Package Test Vehicles

Package Line	Assembly Line	Package	Wire	Die Vehicle / Rawline (*)	Number of Reliability Lots
	MUAR	LQFP7*7 48L	Ag	765 / 5B*765	
	JSCC	LQFP7*7 48L	Ag	766 / 5B*766	
LQFP	JSCC	LQFP10*10 64L	Ag	765 / 5W*765	
	MUAR	LQFP10*10 80L	Au	765 / 1S*765	
QFN	ATP3	UFQFPN3*3 20L	Au	767 / E4*767	3 lots to qualify F9GO1 Technology
QFN	RSST	UFQFPN5*5 32L	Ag	767 / MG*767	Then 1 lot by Package Assembly Line
SO	SHENZHEN	SO8 0,15	Au	767 / 07*767	
30	MUAR	SP20 0,30	Au	767 / 27*767	
TSSOP	SHENZHEN	TSSOP 20 BODY	Ag	767 / YA*767	
PDIP	TONGFU	PDIP 32	Au	766 / 76*766	



## RERMCD1805 – F9GO1 Technology Transfer to ST SG9 (Singapore) STM8S Package Reliability Trials

Reliab	ility Trial & Standard	Test Conditions	Pass Criteria	Lot Strategy	Units per Lot
PC	Pre Conditioning: Moisture Sensitivity Jedec Level 1 J-STD-020/ JESD22-A113  Pre Conditioning: Moisture Sensitivity Jedec Level 3 J-STD-020/ JESD22-A113	Bake (125°C / 24h) Soak (85°C / 85% RH / 168h) for level 1 Convection reflow: 3 passes with Jedec level 1  Bake (125°C / 24h) Soak (30°C / 60% RH / 192h) for level 3 Convection reflow: 3 passes with Jedec level 3	3 Passes MSL1/3	1 to 3 lots	231 to 308 (**)
UHAST (*) (**)	Unbiased Highly Accelerated Temperature & Humidity Stress JESD22-A118	130°C, 85%RH, 2 Atm	96h	1 to 3 lots	77
TC (*)	Thermal Cycling JESD22-A104	-65°C +150°C	500Cy	1 to 3 lots	77
THB (*)	Temperature Humidity Bias JESD22-A101	85°C, 85% RH, bias	1000h	1 to 3 lots	77
HTSL (*)	High Temperature Storage Life JESD22-A103	150°C - no bias	1000h	1 to 3 lots	77
Construction Analysis	JESD22-B102 JESD22-B100/B108	Including Solderability & Physical Dimensions	No concern	1 by package assembly line	15 10
ESD CDM	ESD Charged Device Model ANSI/ESD STM5.3.1	Aligned with device datasheet	250V to 500V	1 by package assembly line	3

<sup>(\*\*)</sup> UHAST not done for BGA

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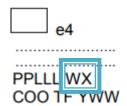
## PRODUCT/PROCESS CHANGE NOTIFICATION PCN 10630 – Additional information

### ST SG9 (Singapore) additional source for STM8S001x, STM8S103x and STM8S903x products

### **MDG - Microcontrollers Division (MCD)**

### How can the change be seen?

The standard marking is:



WX code indicates the diffusion traceability plant code.

Please refer to the <u>DataSheet</u> for marking details.

#### The marking is changing as follows:

Existing		Additional		
WX code	Fab	WX code	Fab	
VG	ST Rousset 8" (France)	VC	ST SG9 8" (Singapore)	

### How to order samples?

For all sample request linked to this PCN, please:

- request sample(s) through Notice tool, indicating a single Commercial
   Product for each request.
- insert "PCN 10630" into the remarks of your order.
- place **non standard** sample order using the following field in your system.

